## 2SD1133, 2SD1134

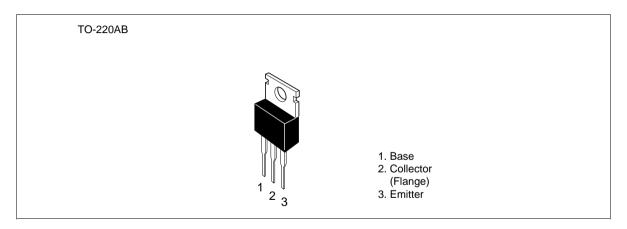
## Silicon NPN Triple Diffused

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### Application

Low frequency power amplifier complementary pair with 2SB857 and 2SB858

## Outline



## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

		Ratings			
Item	Symbol	2SD1133	2SD1134	Unit	
Collector to base voltage	V <sub>CBO</sub>	70	70	V	
Collector to emitter voltage	V <sub>CEO</sub>	50	60	V	
Emitter to base voltage	V <sub>EBO</sub>	5	5	V	
Collector current	Ι <sub>c</sub>	4	4	А	
Collector peak current	C(peak)	8	8	А	
Collector power dissipation	P <sub>c</sub> *1	40	40	W	
Junction temperature	Tj	150	150	°C	
Storage temperature	Tstg	-45 to +150	-45 to +150	°C	

Note: 1. Value at  $T_c = 25^{\circ}C$ .



## 2SD1133, 2SD1134

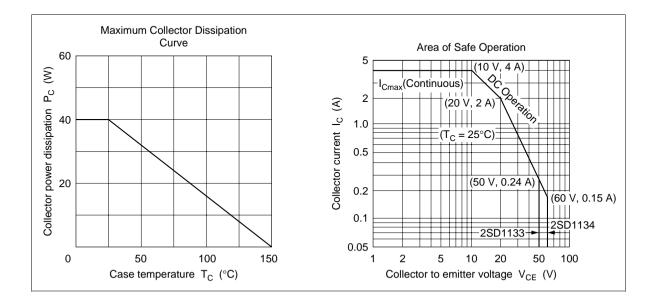
## **Electrical Characteristics** (Ta = 25°C)

		2SD1	133		2SD1134				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	70	—	—	70	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	50	_	_	60		_	V	$I_{c}$ = 50 mA, $R_{BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	—	_	5	_	_	V	$I_{\rm E} = 10 \ \mu {\rm A}, \ I_{\rm C} = 0$
Collector cutoff current	I <sub>cbo</sub>	—		1	—	_	1	μA	$V_{CB} = 50 \text{ V}, \text{ I}_{E} = 0$
DC current transfer ratio	$h_{\text{FE1}}^{*1}$	60		320	60	_	320		$V_{ce} = 4V I_c = 1 A^{*2}$
	$h_{\text{FE2}}$	35		—	35	—	—		$I_{\rm c} = 0.1 \ {\rm A}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	—	1	_	_	1	V	$I_{\rm C} = 2 \text{ A}, I_{\rm B} = 0.2 \text{ A}^{*2}$
Base to emitter voltage	$V_{BE}$	—		1	—	_	1	V	$V_{ce} = 4 \text{ V}, \text{ I}_{c} = 1 \text{ A}^{*2}$
Gain bandwidth product	f <sub>T</sub>	_	7	_	_	7	_	MHz	$V_{ce} = 4 \text{ V}, \text{ I}_{c} = 0.5 \text{ A}^{*2}$

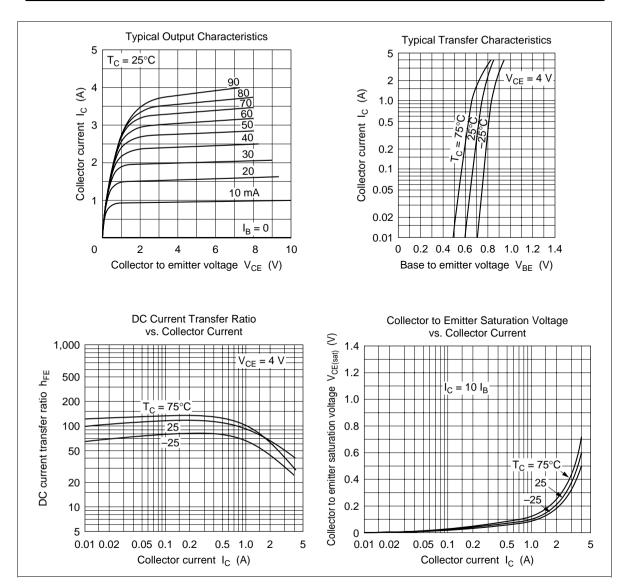
Notes: 1. The 2SD1133 and 2SD1134 are grouped by h<sub>FE1</sub> as follows.

2. Pulse test.

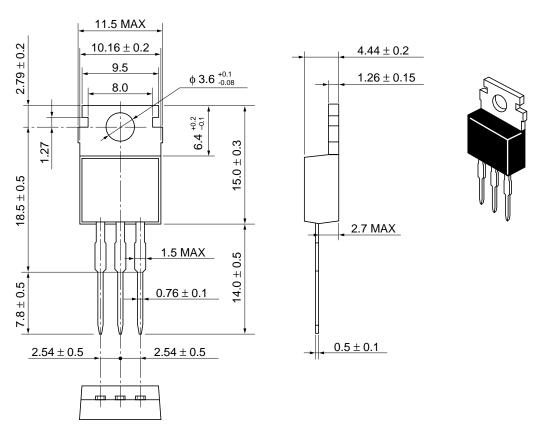
В	С	D
60 to 120	100 to 200	160 to 320



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Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

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